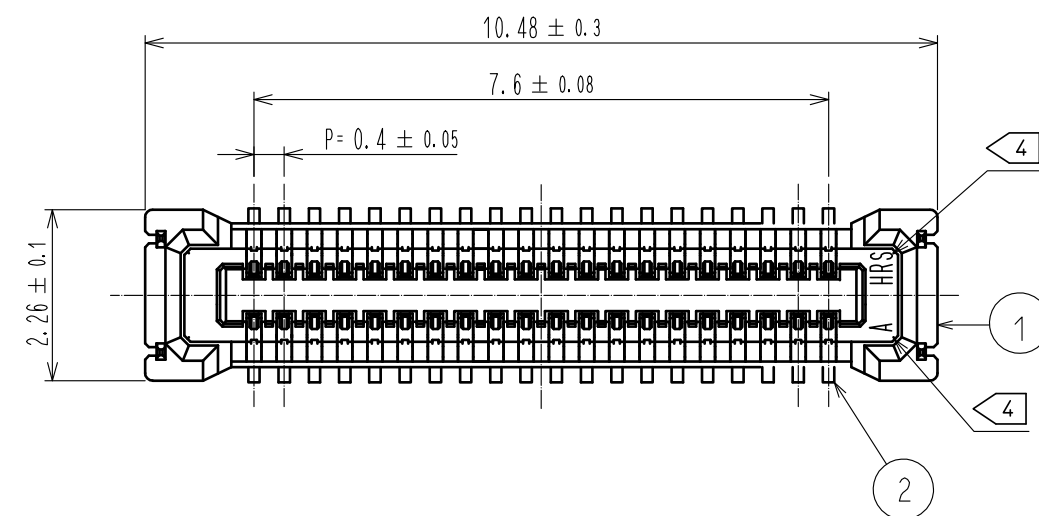


NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2 CONTACT PLATING SPECIFICATIONS

CONTACT AREA : GOLD 0.05μm MIN

SMT LEAD : GOLD 0.05μm MIN

UNDERPLATING : NICKEL 1μm MIN

(SURFACE : SEALING)

3 METAL FITTING PLATING SPECIFICATIONS

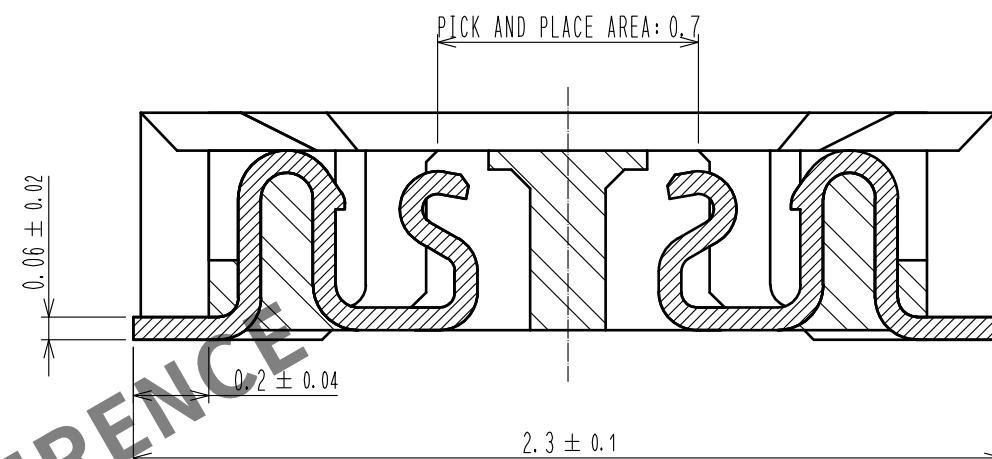
SMT LEAD : GOLD 0.05μm MIN

UNDERPLATING : NICKEL 1μm MIN

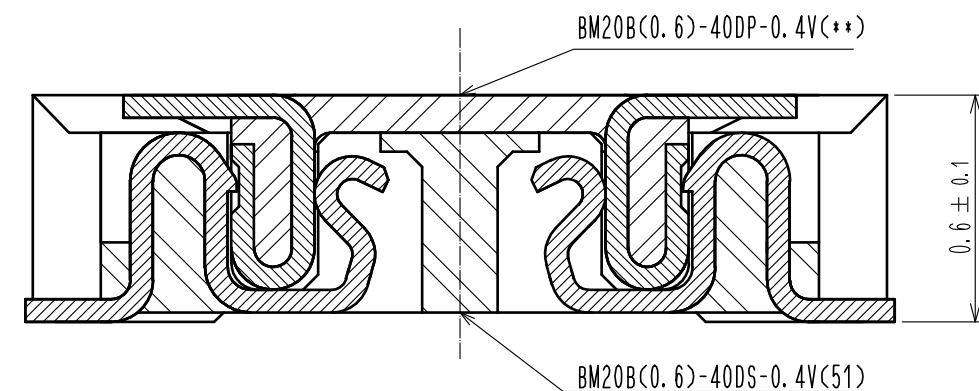
(SURFACE : SEALING)

4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

A-A(50:1)

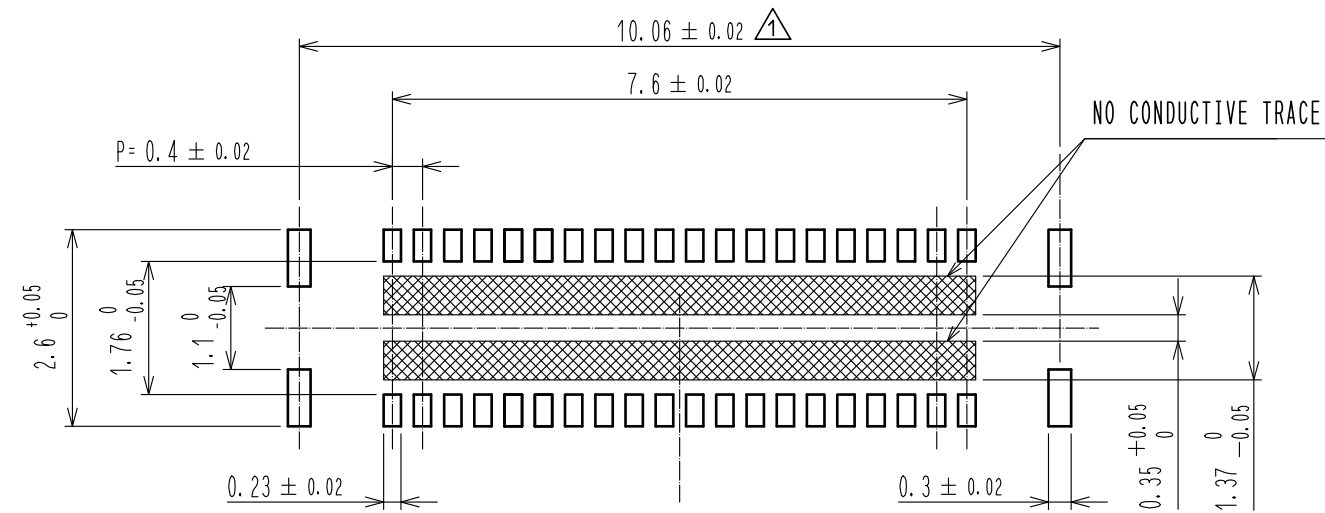


ENGAGEMENT FIGURE (50:1)



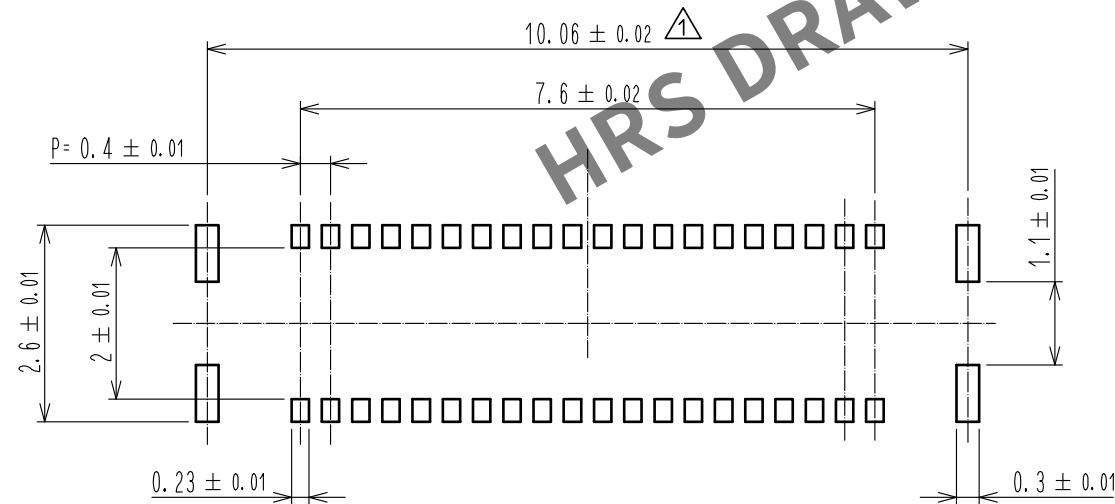
4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	BRASS	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 3	DESCRIPTION OF REVISIONS DIS-H-00003231	DESIGNED RT. SHIMIZU
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	13. 07. 11	DRAWING NO.	EDC3-347100-01
		CHECKED : WR. FUKUCHI	13. 07. 11	PART NO.	BM20B(0.6)-40DS-0.4V(51)
		DESIGNED : RT. SHIMIZU	13. 07. 10	CODE NO.	CL684-9313-8-51
		DRAWN : Hongwoo. Jo	13. 07. 09		
				DATE	17. 11. 02
				CHECKED	TS. MIYAZAKI

◆RECOMMENDED PCB LAYOUT

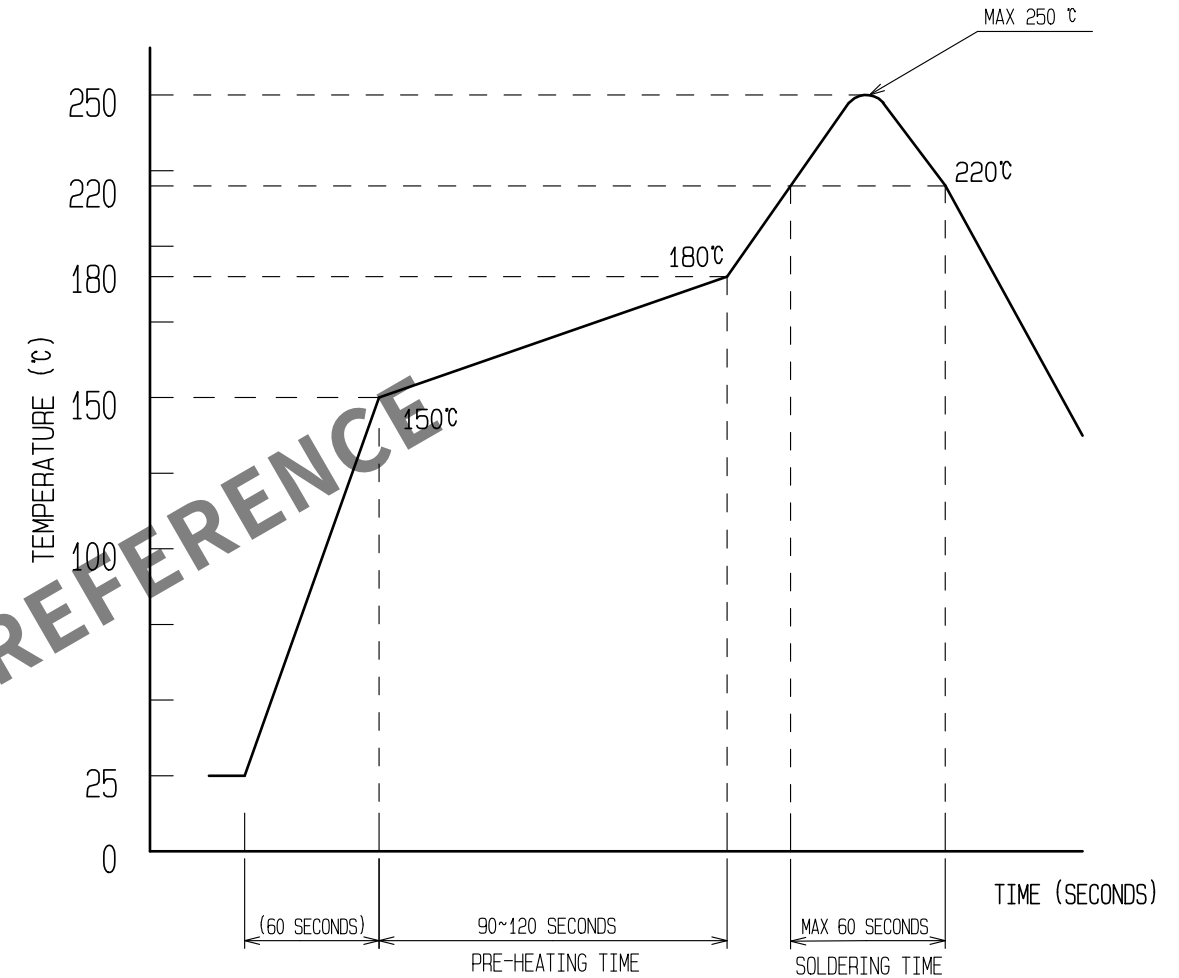


◆RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

5 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-347100-01
PART NO.	BM20B(0.6)-40DS-0.4V(51)
CODE NO.	CL684-9313-8-51

1/2/3

